

Features

- Low voltage operation
- Low current consumption
- Miniature SMD package size
- I²C communication protocol
- Reliable capacitive technology
- Relative humidity accuracy of ±2 % (Typical)

Applications

Industrial:

- HVAC systems
- Process monitoring
- Packaging automation
- **Medical Devices (low/medium risk):
- Diagnostic equipment
- Analysis equipment

BPS230 Series - 2 mm Humidity Sensor

Supply Voltage (V _{CC})	0.3 to 7.0 V
nput Voltage (V _I)	
CE	
SCL/SDA	
Output Voltage (VO)	0.3 to V _{cc} + 0.3 V
fi-level Output Current (IOH)	
1 Terminal	
All Terminals Total	20 M/
.ow-level Output Current (IOL) 1 Terminal	5 m/
All Terminals Total	
Operating Temperature (T _a)	
Storage Temperature (T _{sto})	
Recommended Operating Conditions	
Power Supply Voltage (V _{CC})	
Capacitance between V _{cc} and V _{ss} (C _p)	0.1 μF typica
Pull Up Resistor Value on SDA ¹ (R1)	
Pull Up Resistor Value on SCL ¹ (R2)	5 kΩ typica
Select the resistance value to meet AC characteristics.	
Electrical Characteristics	
Humidity Detection	
Measurement Range	
Resolution (10-bit)	0.1 % RH typica
Humidity Accuracy - Typical (see Humidity Sensor Accuracy Graph for Maximum Rating)	0.04 PU
@ 25 °C (20 to 80 % RH)	
@ 5 °C to 45 °C (0 to 100 % RH)	
Response Time	± 1 % nn typica
Reach (τ 63 % @ 25 °C, wind velocity @ 1.0 m/s)	8 seconds
Unless otherwise specified: V_{CC} = 1.62 to 5.5 V, V_{SS} = 0 V, T_a = -20 °C to 100 °C	
emperature Detection	
Measurement Range	30 °C to +100 °C (-22 °F to +212 °F)
Resolution (11 bit)	
-10 °C to +70 °C	•
All other temperatures	0.4 °C (0.72 °F)
· · · · · · · · · · · · · · · · · ·	2 4 2 2 4 2 7 2 7 2
Temperature Accuracy	
['] @ 5 °C to 60 °C	
[°] @ 5 °C to 60 °C. [°] @ -20 °C to 85 °C	± 1.0 °C (±1.8 °F
e 5 °C to 60 °C	± 1.0 °C (±1.8 °F
@ 5 °C to 60 °C. @ -20 °C to 85 °C Reproducibility @ -30 °C to 100 °C.	± 1.0 °C (±1.8 °F ± 0.1 °C (±0.18 °F
e 5 °C to 60 °C. e -20 °C to 85 °C. Reproducibility @ -30 °C to 100 °C	± 1.0 °C (±1.8 °F ± 0.1 °C (±0.18 °F
@ 5 °C to 60 °C. @ -20 °C to 85 °C Reproducibility @ -30 °C to 100 °C.	± 1.0 °C (±1.8 °F ± 0.1 °C (±0.18 °F

Current Consumption

Unless otherwise specified: V_{CC} = 1.62 to 5.5 V, V_{SS} = 0 V, T_a = 0 °C to 60 °C

- RoHS3 Directive 2015/863 Amendments of Annex II on March 31, 2015
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Users should verify actual device performance in their specific applications.

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Input/Output Terminal Characteristics

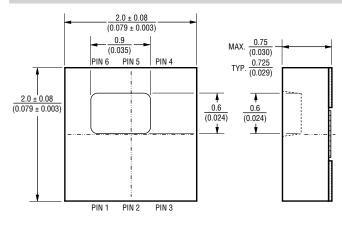
High Level Input Voltage 1 (VIH1) [Target Terminal: SCL, SDA]	0.7 V _{cc} minimum, V _{cc} maximum
High Level Input Voltage 2 (VIH2) [Target Terminal: CE]	0.8 V _{cc} minimum, V _{cc} maximum
Low Level Input Voltage 1 (VIL1) [Target Terminal: SCL, SDA]	V _{ss} minimum, 0.3 V _{cc} maximum
Low Level Input Voltage 2 (VIL2) [Target Terminal: CE]	V _{ss} minimum, 0.2 V _{cc} maximum
Low Level Output Current (IOL) [VOL = 0.1 V _{CC} , Target Terminal: SCL, SDA]	0.5 mA minimum
Terminal Leak Current 1 (IL1) [Terminal voltage = V _{CC} , Target Terminal: SCL, SDA]	± 1 μA
Terminal Leak Current 2 (IL2) [Terminal voltage = 0 V, Target Terminal: SCL, SDA, CE]	± 1 μA
Input Pull-Down Resistance (RPD) [Terminal voltage = V_{CC} , Target Terminal: CE]60 k Ω minimum,	, 150 k Ω typical, 450 k Ω maximum

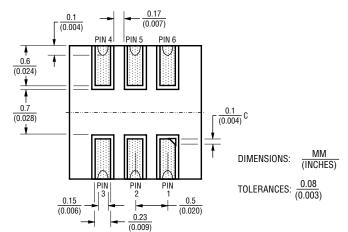
Unless otherwise specified: V_{CC} = 1.62 to 5.5 V, V_{SS} = 0 V, T_a = -30 °C to 100 °C

Product Characteristics

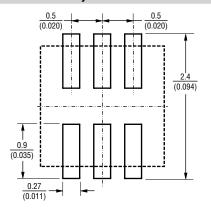
Moisture Sensitivity Level	1
ESD Classification (HBM)	1 kV
Marking	
Standard Packaging	
Weight	0.059 grams (0.002 oz)

Product Dimensions





Recommended PCB Layout



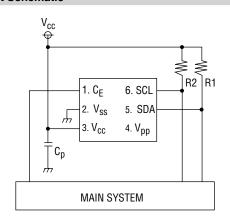
Terminal Assignment

No.	Terminal Name	Function
1	CE	Chip enable terminal
2	V_{ss}	Power supply terminal (-)
3	V_{cc}	Power supply terminal (+)
4	NC	No connection
5	SDA	I ² C serial data
6	SCL	I ² C serial clock

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Basic Circuit Schematic



C_p 0.1 μF R1 5k Ω R2 $5k \Omega$

NOTE: R1 and R2 are reference values. Resistor values should be selected to meet the AC characteristics.

Operation Mode

Operation	Terminal Setup	Operation State of Each Functional Block						
Mode	CE	V _{pp}	Power Supply	Oscillation	Temp. Detection	Capacitance Detection	OTP Memory	I ² C-Bus
Sleep *1	0	NC	Stop	Stop	Stop	Stop	Stop	Stop
Standby	1	NC	Operation	Operation	Stop	Stop	Read-out Possible	Operation

^{*1} In case of power control mode, there is no sleep operation. I²C slave address (SADR) is defined as "111 1111" (7Fh).

Control Register Map

Address	Bit	Bit Name	Function	Value	ReadOut	Write-In	R/W	Init.			
	D7-1	-	Reserved	-			R	0			
00h	00h	RESET	Γ Reset	0	Normal Operation	None	R/W	0			
				1	-	Reset Action					
	D7-6	MANMODE	Manual Detection Mode	00	Normal Operation Mode						
	D5-3 HAVE[2:0]			Humidity	000	No Averagi	ing Process	R/W	0		
		LIAVE[0.0]	Detection	001	2 Times Av	erage Mode					
01h		D5-3	D5-3	HAVE[2:0]	HAVE[2.0]	75-5 HAVE[2.0]	Value Avg.	01x	4 Times Av	erage Mode	
			Mode 1xx		8 Times Average Mode						
		TAVE	Temperature	0	8 Times Av	erage Mode					
	D2		Detection Value Avg. Mode	1	16 Times Av	verage Mode	R/W	0			

Control Register Map (Continued)

Address	Bit	Bit Name	Function	Value	ReadOut	Write-In	R/W	Init.
	D1	-	Reserved	-			R	0
01h	D0	MAN	Manual Detection	Standby State Detection Operation Stop	- R/W	0		
	D0	IVIAIN	Mode		Under Detection Operation	ction Operation	1 H/VV	U
	D7-1	-	Reserved	-			R	0
03h	D0	FDD	Manual	0	No Error	Nothing is Done	DAM	
	D0	ERR	Detection Error Flag	1	Error Occurred	Error Flag Reset	R/W	0
04h	D7-0	HC[7:0]	Humidity Detection Result (After Correction Operation)		000h-3FFh		R	Х
	D7-2	-	Reserved	-			R	0
05h	D1-0	HC[9:8]	Humidity Detection Result (After Correction Operation)				R	Х
06h	D7-0	TC[7:0]	Temperature Detection Result (After Correction Operation)		000h-7FFh		R	Х
	D7-3	-	Reserved	-			R	0
07h	D2-0	TC[10:8]	Temperature Detection Result (After Correction Operation)				R	Х
0Ah	D7-0	K[7:0]	Capacity Detection Result (Before Correction Operation)		000h-FFFFh		R	0

Control Register Map (Continued)

Address	Bit	Bit Name	Function	Value	ReadOut	Write-In	R/W	Init.
0Bh	D7-0	K[15:8]	Capacity Detection Result (Before Correction Operation)				R	0
	D7-5	-	Reserved	-	-	-	R	0
			Standard	0	Outside Capacity Cutting			
2Ch	D4 SCR_ON_R	Capacity Connection Control	1 Outside Capacity Connection		R/W	0		
	D3-0	SCI_ ON_R[3:0]	Internal Capacity Connection Control	0h~Fh x 0.6 pF Example: At the time of 8 hours, access to internal capacity of 4.8 pF		R/W	Х	
	D7-1	-	Reserved	-		R	0	
03h D0		Manual		0	No Error	Nothing is Done	5	
		Detection Error Flag	1	Error Occurred	Error Flag Reset	R/W	0	

Transfer Function Formula

Humidity

RH =
$$\frac{100}{2^{10}}$$
 x RH_{IC} (0 ~ 100 % RH)

RH_{IC}: IC Humidity Output Data (10 bit)

Refer to Register Map:

 RH_{IC} = Data of the addresses 04H and 05H (000h ~ 3FFh) It changes into a decimal and is operation.

Temperature

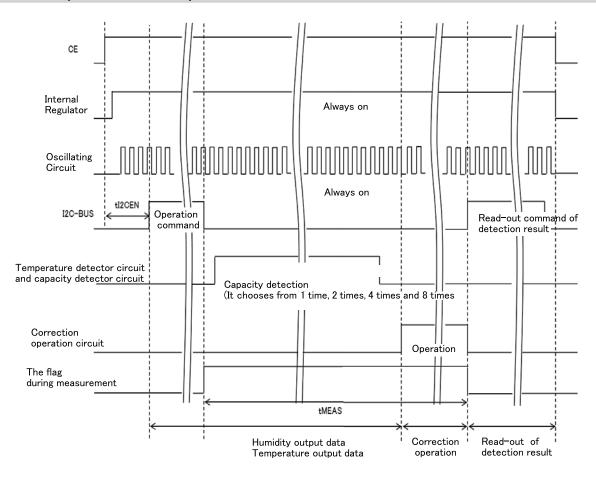
T =
$$[T_{IC} - (2^{10} - \frac{25}{0.1})] \times 0.1$$
 (-30 ~ 100 °C)

T_{IC}: IC Temperature Output Data (11 bit)

Refer to Register Map:

 T_{IC} = Data of the addresses 06H and 07H (000h ~ 7FFh) It changes into a decimal and is operation.

Capacitance/Temperature Detection Sequence

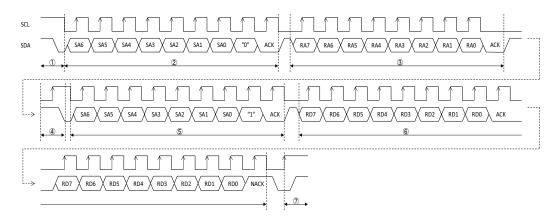


How To Order BPS230 - D 3P0 - S 10 E Model Series Humidity-Temperature Sensor Output Type D = Digital Accuracy (% RH) 3P0 = ±3.0 Moisture Sensitivity S = Standard Resolution 10 = 10-bit Packaging Designator E = 3000 pcs. per 7-inch Reel

Output Type Waveform and Data Read/Write Procedure

I²C-BUS Data Read-out Procedure

- 1) I²C master device releases START condition.
- (2) I²C master device transmits slave address and WRITE mode selection.
- (3) I²C master device transmits register address of this IC.
- (4) I²C master device releases repeated START condition. (Release method is same as START condition.)
- (5) I²C master device again transmits slave address and READ mode selection. (Read mode can be selected by transmitting "1" in 8th bit.)
- 6 I2C master device reads-out data from register address designated at ③.
 It is possible to read-out data while register address increments one, by reading-out multiple data continuously. However, during continuous read-out, please return ACK to this IC as a reply of master.
- 7) After the completion of all read-out, I²C master device releases STOP condition.



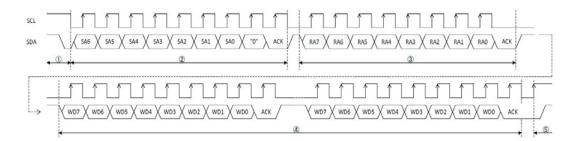
~ Continued ~

Output Type Waveform and Data Read/Write Procedure (Continued)

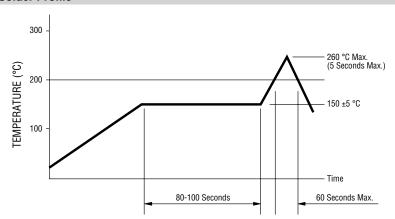
I2C-BUS Data Write-in Procedure

- (1) I²C master device releases START condition. (Start condition can be released by changing SDA from "H" to "L" while SCL is in "H" state.)
- 2 I²C master device transmits slave address and WRITE mode selection. (Write mode can be selected by transmitting "0" in 8th bit while 1~7th bits are slave address.)
- (3) I²C master device transmits register address of this IC.
- (4) I²C master device transmits write-in data.
- (5) It is possible to write-in data while register address increments one, by transmitting multiple write-in data continuously.

After the completion of transmitting all write-in data, I²C master device releases stop condition. (Stop condition can be released by changing SDA from "L" to "H" while SCL is in "H" state.)



Solder Profile



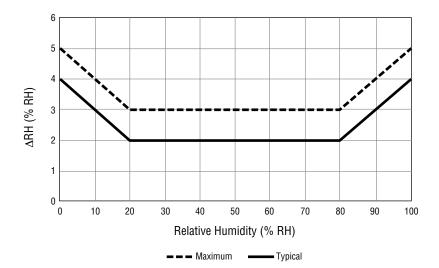
Processing Method: Reflow soldering with infrared heat or forced air convection (only once).

Notes:

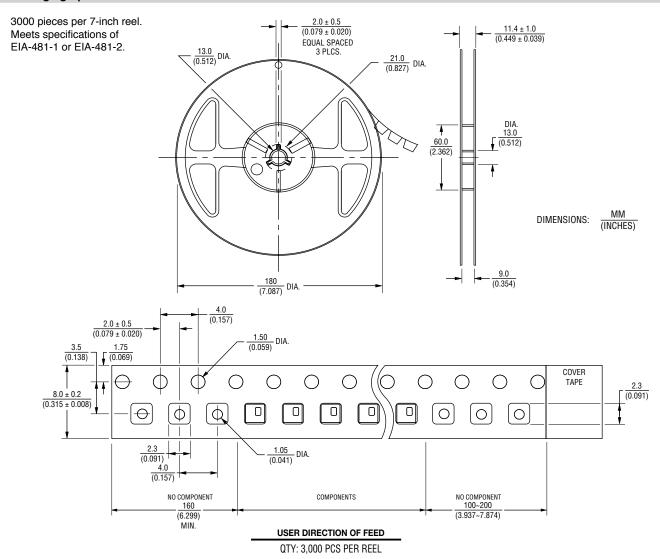
- 1. No clean solder paste is recommended.
- 2. Aqueous wash is not recommended.
- Use of water soluble soldering flux should be avoided due to possible corrosion.
- 4. Multiple passes through the soldering process is not recommended.
- Other SMD processes and profiles should be verified by the customer.

Humidity Sensor Accuracy

Relative Humidity (% RH)	Maximum	Typical
0	5	4
10	4	3
20	3	2
30	3	2
40	3	2
50	3	2
60	3	2
70	3	2
80	3	2
90	4	3
100	5	4



Packaging Specification



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